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REMARKS

Claims 2-4, 7-9, 11, 13 and 28 have been amended. Claim 32 has been added. Claims 1, 5-6, 17-27 and 30 have been canceled. Claims 2-4, 7-16, 28-29 and 31 remain pending in the application. Applicant respectfully reserves the right to pursue the original claims and other claims in this or any other application. Applicant respectfully requests reconsideration in light of the following remarks.

Claims 2-4, 7, 11-13, 15, 16 and 28-31 stand rejected under 35 U.S.C. § 103(a) as being unpatentable over Shibata in view of Anderton, U.S. Patent No. 5,596,228. Shibata refers to a light sensitive chip coated with a polyimide resin which has organic color pigments within it. Amended claims 7 and 28 each recite “an optical light transmitting device covering said photosensitive elements.” Shibata does not teach or suggest this feature. The Office Action also acknowledges that Shibata does not teach photosensitive elements that are arranged in a two dimensional array.

Anderton refers to an apparatus for cooling charge coupled devices (CCD). Anderton discusses the use of charge-coupled device arrays. Because Anderton relates to cooling devices for CCDs and Shibata relates to a light sensitive chip coated with polyimide, there is no motivation or suggestion in the references to arrive at the claimed invention through the combination of these disparate references.

Claims 2-4 depend from claim 7 and incorporate all the limitations of claim 7 plus additional limitations and are therefore allowable for at least the reasons stated above for claim 7. Claims 29 and 31 depend from claim 28 and incorporate all the limitations of claim 28 plus additional limitations and are allowable for at least the reasons stated above for claim 28.

Amended claim 11 recites an “image source capable of simultaneously transmitting an image to a plurality of semiconductor devices.” The Office Action acknowledges that Shibata does not teach an image source for transmitting an image.

Furthermore, Shibata does not teach an “image source capable of simultaneously transmitting an image to a plurality of semiconductor devices,” as recited in claim 11. Anderton is cited in the Office Action for another feature. Claims 12-16 depend from claim 11 and incorporate all the limitations of claim 11 plus additional limitations and are allowable for at least the reasons stated above for claim 11.

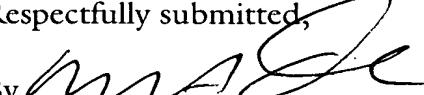
Claim 8 stands rejected under 35 U.S.C. § 103(a) as being unpatentable over Shibata in view of Koo, U.S. Patent No. 6,169, 295. Claim 8 is dependent from claim 7 and therefore should be allowable for at least the reasons stated above for claim 7. Koo discloses an infrared transceiver module with a sensor and emitter. Koo does not disclose an imaging device and the lens used in Koo is reflective in order to form a reflective cup for the emitter. Shibata, as acknowledged in the Office Action, does not disclose a lens associated with the light sensitive device of its invention. It would not have been obvious to combine the disparate teachings of the reflective lens of the non-imaging device disclosed in Koo with the light sensitive device disclosed in Shibata.

Claims 9, 10 and 14 stand rejected under 35 U.S.C. § 103(a) as being unpatentable over Shibata in view of Koo and further in view of Iida, U.S. Patent No. 5,278,009. Claims 9 and 10 depend from claim 7 and claim 14 depends from claim 11 and should be allowable along with claims 7 and 11 and for other reasons.

In view of the above, each of the presently pending claims in this application is believed to be in immediate condition for allowance. Accordingly, the Examiner is respectfully requested to withdraw the outstanding rejection of the claims and to pass this application to issue.

Attached hereto is a marked-up version of the changes made to the claims by the current amendment. The attached page is captioned "Version with markings to show changes made."

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Version With Markings to Show Changes Made

2. (Amended) The imaging device of claim 7 [The semiconductor device of claim 1], wherein said photosensitive elements are arranged in a two-dimensional array.

3. (Amended) The imaging device of claim 7 [The semiconductor device of claim 2], wherein said transparent plastic material includes injection molded epoxy resin.

4. (Amended) The imaging device of claim 7 [The semiconductor device of claim 3], further comprising leads connected to said semiconductor material, said leads being partially encapsulated in said transparent plastic material.

7. (Amended) An imaging device, comprising:

a package formed of transparent plastic material;

a semiconductor chip encapsulated [located] within said package, said chip including an array of photosensitive elements for receiving an image and for generating corresponding signals, said photosensitive elements being covered by said transparent plastic material; and

an optical light transmitting device covering said photosensitive elements.

8. (Amended) The imaging device of claim 7, wherein [said package includes a lens for transmitting the image onto said photosensitive elements, said lens] said optical light transmitting device being formed of said transparent plastic material.

9. (Amended) The imaging device of claim 7, wherein said optical light transmitting device is a [package includes] color filter, said filter being formed of said transparent plastic material.

11. (Amended) An imaging system, comprising:

a system for transmitting an image including an image source and plurality of semiconductor devices; [an image source for transmitting an image; a first semiconductor device for receiving the image and for generating corresponding signals; and]

said image source capable of simultaneously transmitting an image to a plurality of semiconductor devices;

wherein said plurality of semiconductor devices includes first, second and third semiconductor devices for receiving the image and for generating corresponding signals; and first, second and third packages for protecting and supporting each said first second and third semiconductor device, said packages being formed of transparent plastic material, said plastic material including injection molded resin for transmitting an image from said image source onto said first, second and third semiconductor devices [a first package for protecting and supporting said semiconductor device, said package being formed of transparent plastic material, said plastic material including injection molded resin for transmitting an image from said image source onto said first semiconductor device].

13. (Amended) The system of claim 11, wherein said first, second and third semiconductor devices include complementary color filters [further comprising second and third semiconductor devices, and second and third packages for protecting and supporting said second and third semiconductor devices, said second and third packages including injection molded resin, and wherein said image source is arranged to simultaneously transmit the image onto said first, second and third semiconductor devices, and wherein said first, second and third semiconductor devices include complementary color filters].

28. (Amended) An imaging device, comprising:

a package formed of a housing, wherein said housing is formed of a ceramic material, and a transparent plastic cover;

an optical light transmitting device covering said photosensitive elements; and

a semiconductor chip located within said package, said chip including an array of photosensitive elements for receiving an image and for generating corresponding signals, said photosensitive elements being covered by said transparent plastic cover.